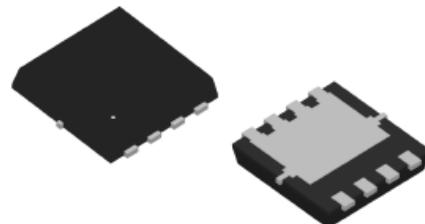


## WNM3034

**SingleN-Channel, 30V, 19A, Power MOSFET**

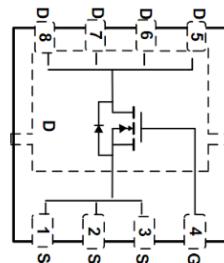
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

<b>V<sub>DS</sub> (V)</b>	<b>Typical R<sub>DS(on)</sub> (mΩ)</b>
30	12 @ V <sub>GS</sub> =10V
	16 @ V <sub>GS</sub> =4.5V



The WNM3034 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM3034 is Pb-free.

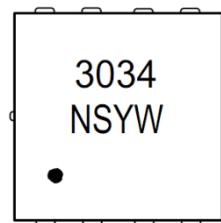
**PDFN3X3-8L**



### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package PDFN3X3-8L-EP

**Pin configuration (Top view)**



NS = Device Code  
 Y = Year  
 W = Week(A~z)

### Applications

#### Marking

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

#### Order information

<b>Device</b>	<b>Package</b>	<b>Shipping</b>
WNM3034-8/TR	PDFN3*3-8L	3000/Tape&Reel

## Absolute Maximum ratings

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	
Continuous Drain Current <sup>d</sup>	I <sub>D</sub>	19	A
		18	A
Pulsed Drain Current <sup>c</sup>	I <sub>DM</sub>	56	A
Continuous Drain Current	I <sub>DSM</sub>	12	A
		9	
Avalanche Energy L=0.3mH	E <sub>AS</sub>	12	mJ
Power Dissipation <sup>b</sup>	P <sub>D</sub>	13	W
		8.3	
Power Dissipation <sup>a</sup>	P <sub>DSM</sub>	3.6	W
		2.3	
Operating Junction Temperature	T <sub>J</sub>	-55 to 150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C

## Thermal resistance ratings

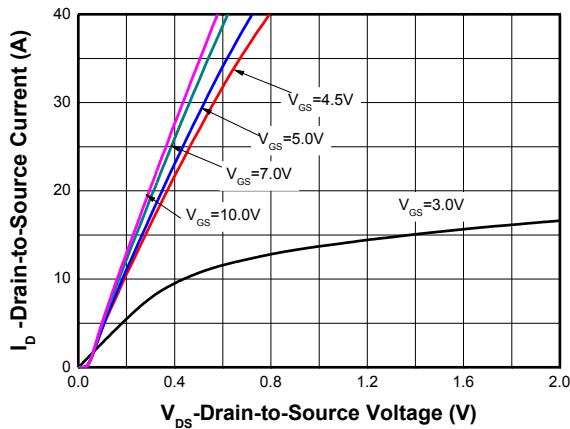
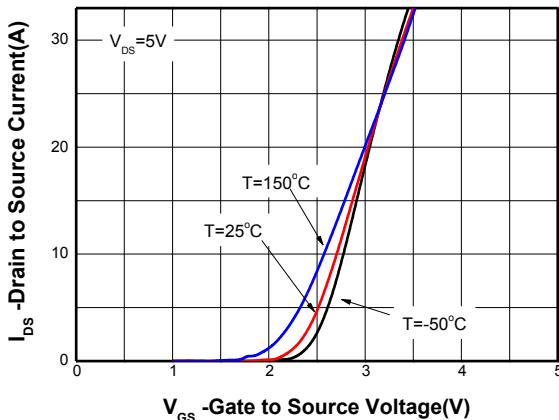
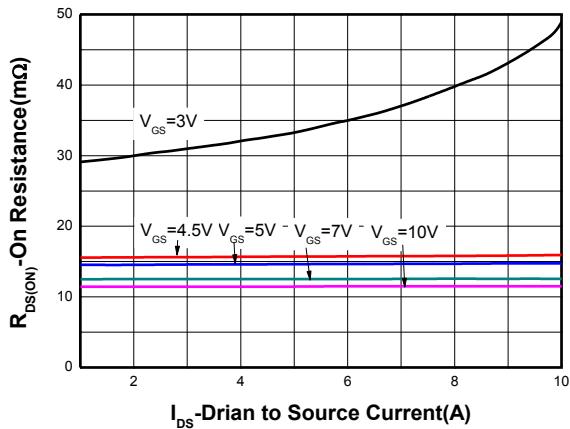
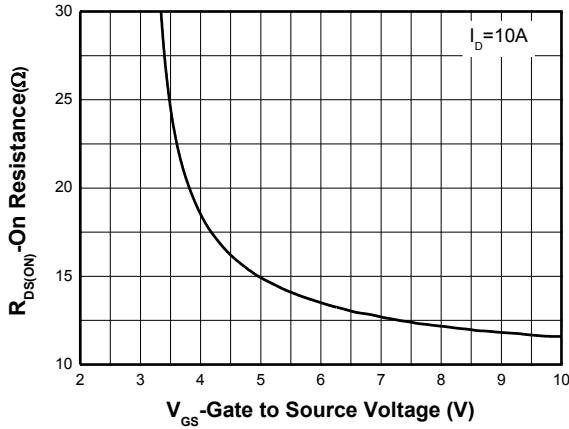
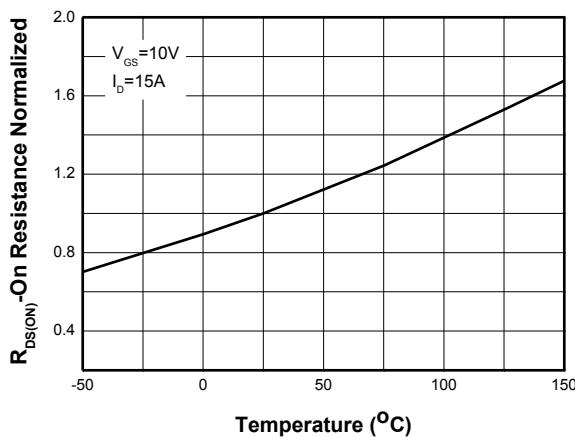
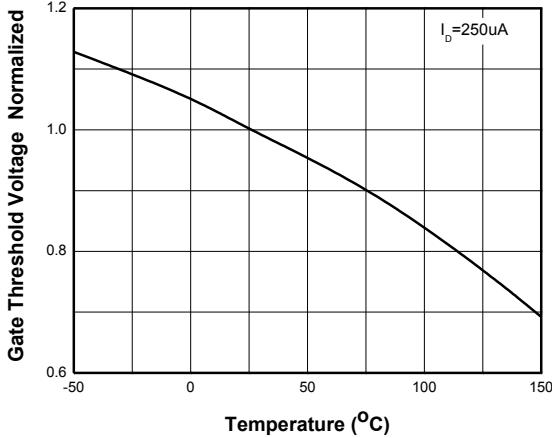
Single Operation					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance <sup>a</sup>	t ≤ 10 s	R <sub>θJA</sub>	28	35	°C/W
	Steady State		53	67	
Junction-to-Case Thermal Resistance	Steady State	R <sub>θJC</sub>	8	9.6	

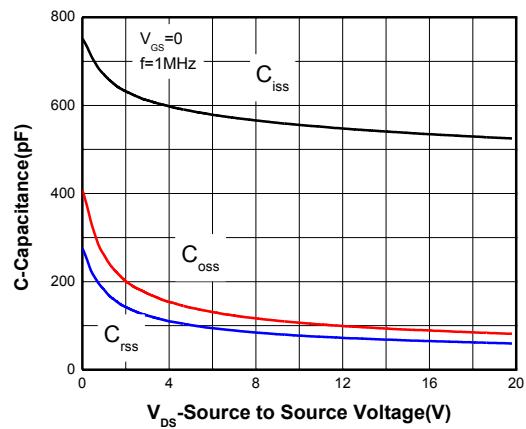
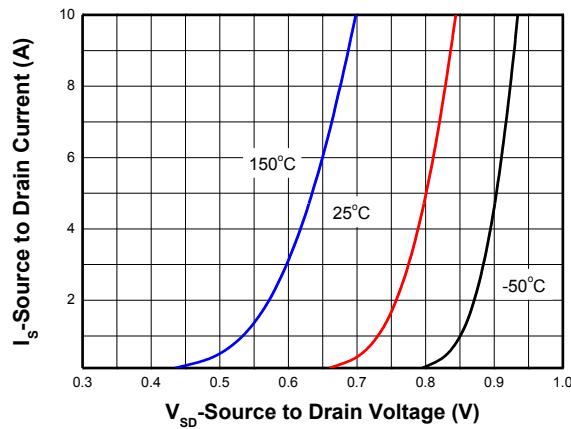
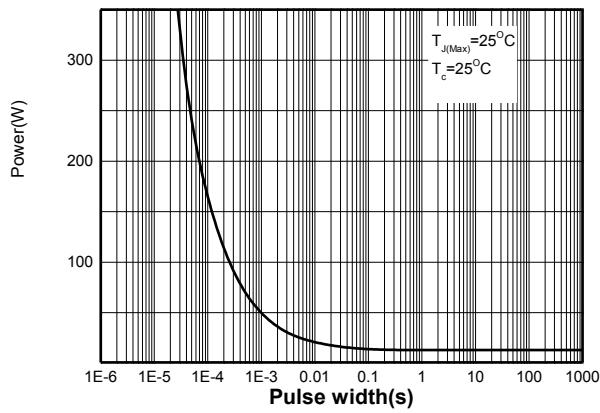
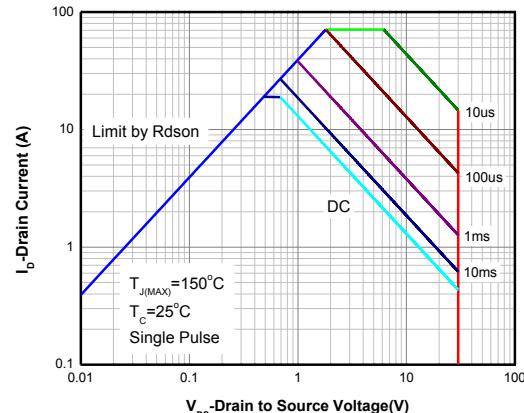
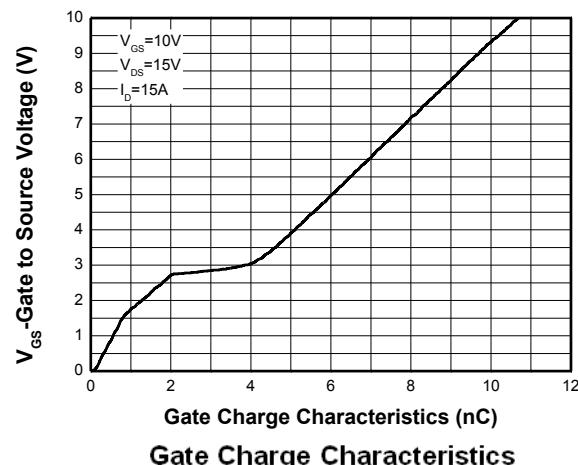
### Note:

- a The value of R<sub>θJA</sub> is measured with the device mounted on 1-inch<sup>2</sup> (6.45cm<sup>2</sup>) with 2oz.(0.071mm thick) Copper pad on a 1.5\*1.5 inch<sup>2</sup>, 0.06-inch thick FR4 PCB, in a still air environment with T<sub>A</sub> =25°C. The power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> t≤10s value and the T<sub>J(MAX)</sub>=150°C. The value in any given application is determined by the user's specific board design.
- b The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- c Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial T<sub>J</sub> =25°C, the maximum allowed junction temperature of 150°C.
- d The maximum current rating by source bonding technology.
- e The static characteristics are obtained using ~380us pulses, duty cycle ~1%.
- f Guaranteed by design.

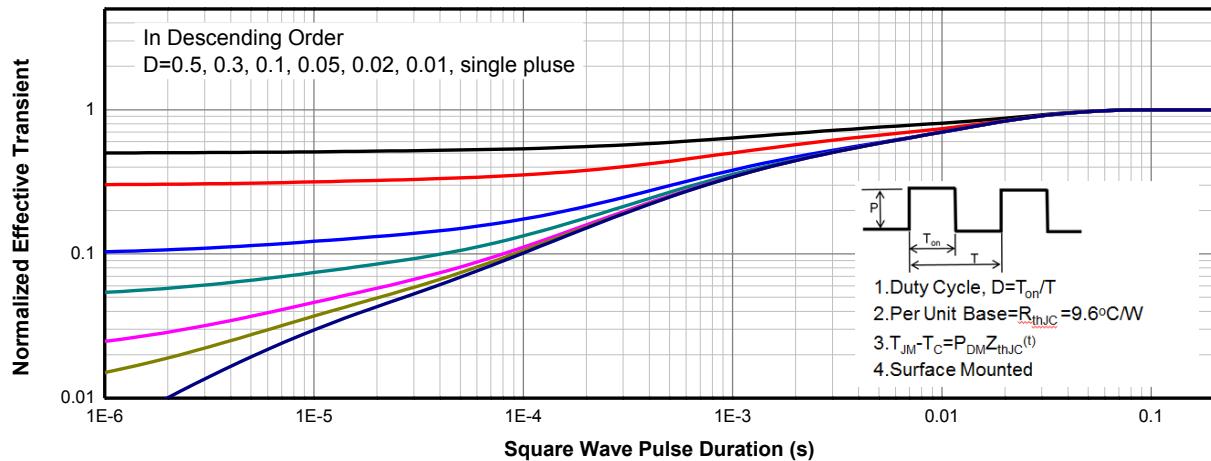
**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250uA	30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V			1	uA
Gate-to-source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20V			±100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250uA	1.2	1.7	2.5	V
Drain-to-source On-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A		12	15	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 8A		16	23	
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0MHz, V <sub>DS</sub> = 15 V		540		pF
Output Capacitance	C <sub>OSS</sub>			95		
Reverse Transfer Capacitance	C <sub>RSS</sub>			68		
Total Gate Charge <sup>f</sup>	Q <sub>G</sub> (10V)	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		10.6	19.1	nC
	Q <sub>G</sub> (4.5V)			5.5	10.0	
Threshold Gate Charge	Q <sub>G(TH)</sub>			1		
Gate-to-Source Charge	Q <sub>GS</sub>			1.9		
Gate-to-Drain Charge	Q <sub>GD</sub>			2.1		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	t <sub>d(ON)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 15 V, R <sub>L</sub> =1 Ω , R <sub>G</sub> =3Ω		4		ns
Rise Time	t <sub>r</sub>			17		
Turn-Off Delay Time	t <sub>d(OFF)</sub>			18		
Fall Time	t <sub>f</sub>			9		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1A		0.7	1	V

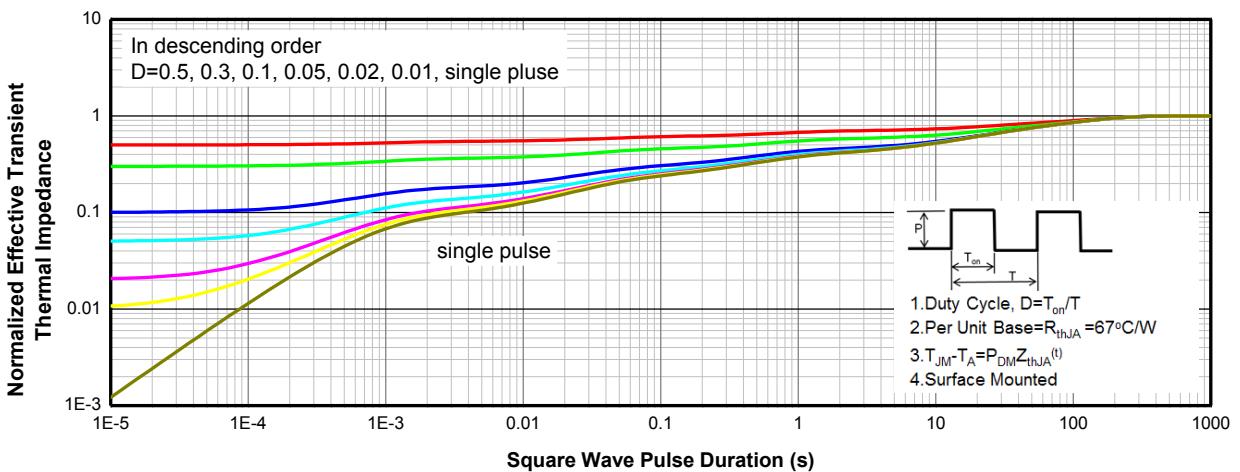
**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output Characteristics <sup>e</sup>**

**Transfer Characteristics <sup>e</sup>**

**On-Resistance vs. Drain Current <sup>e</sup>**

**On-Resistance vs. Gate-to-Source Voltage <sup>e</sup>**

**On-Resistance vs. Junction Temperature <sup>e</sup>**

**Threshold voltage vs. Temperature**

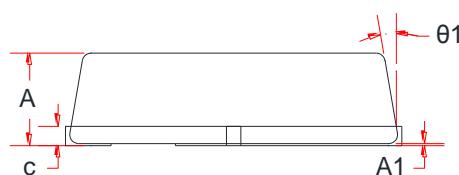
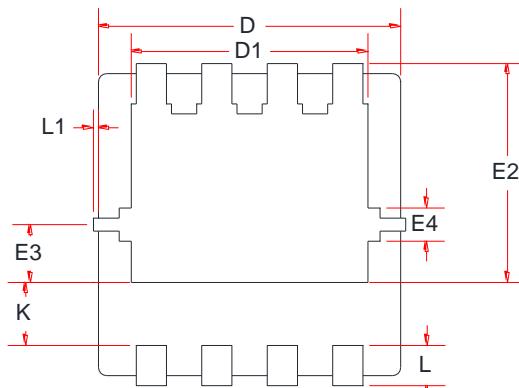
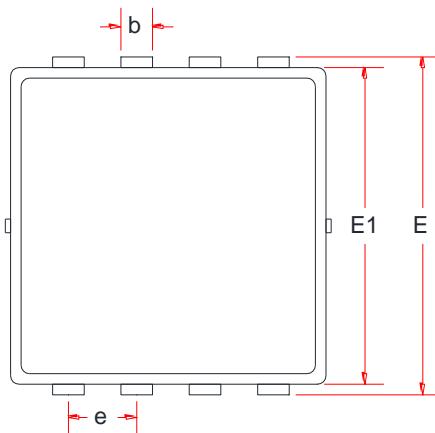

**Capacitance**

**Body Diode Forward Voltage <sup>e</sup>**

**Single pulse power**

**Safe operating power**

**Gate Charge Characteristics**

### Transient Thermal Response (Junction-to-Case)

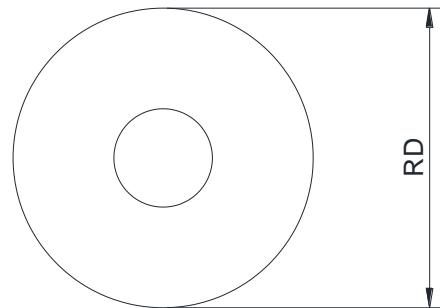
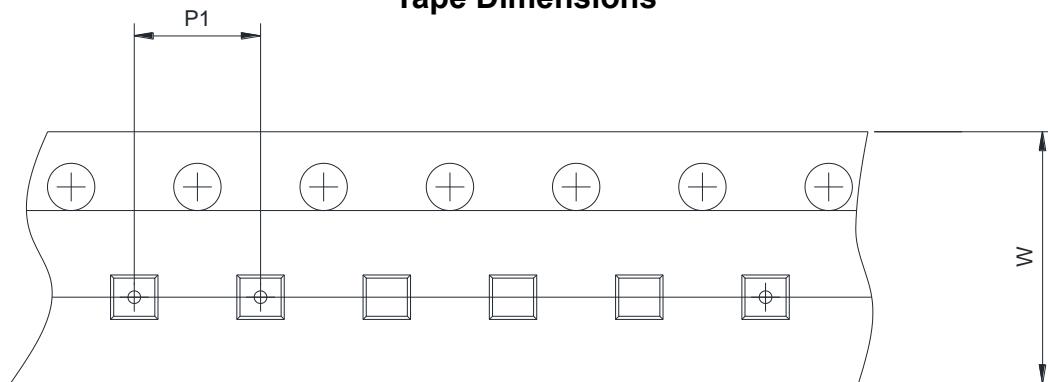
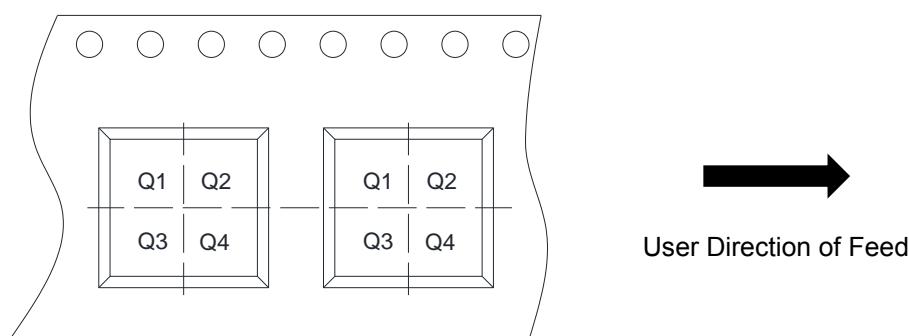


### Transient Thermal Response (Junction-to-Ambient)



**PACKAGE OUTLINE DIMENSIONS**
**PDFN3x3-8L**


Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.80	0.90
A1	0.00	-	0.05
c	0.10	0.15	0.25
b	0.24	0.30	0.35
D	3.00 BSC		
D1	2.25	2.35	2.45
E	3.20 BSC		
E1	3.00 BSC		
E2	2.02	2.18	2.33
E3	0.48	0.58	0.68
E4	0.33 BSC		
e	0.65 BSC		
K	0.47	0.63	0.78
L	0.30	0.40	0.50
L1	0	-	0.10
θ	0 °	10 °	12 °

**TAPE AND REEL INFORMATION**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


RD	Reel Dimension	<input type="checkbox"/> 7inch <input checked="" type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input type="checkbox"/> 8mm <input checked="" type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm <input type="checkbox"/> 4mm <input checked="" type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1 <input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4